

1 **DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

2 As the below named inventor, I hereby declare that:

3 My residence, post office address and citizenship are as stated
4 below next to my name.5 I believe I am the original, first and joint inventor of the subject
6 matter which is claimed and for which a patent is sought on the
7 invention entitled: An Epoxy, Epoxy System, and Method of Forming
8 a Conductive Adhesive Connection, the specification of which is attached
9 hereto.10 I hereby state that I have reviewed and understand the contents
11 of the above-identified specification, including the claims.12 I acknowledge the duty to disclose information known to me to
13 be material to patentability as defined in Title 37, Code of Federal
14 Regulations §1.56.15 **PRIOR FOREIGN APPLICATIONS:**16 I hereby state that no applications for foreign patents or inventor's
17 certificates have been filed prior to the date of execution of this
18 declaration.19 **POWER OF ATTORNEY:**20 As a named Inventor, I hereby appoint the following attorneys and
21 agent to prosecute this application and transact all business in the
22 Patent and Trademark Office connected therewith: Richard J. St. John,
23 Reg. No. 19,363; David P. Roberts, Reg. No. 23.032; Randy A. Gregory,
24 Reg. No. 30,386; Mark S. Matkin, Reg. No. 32,268; James L. Price, Reg.E
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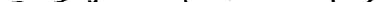
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7 Send correspondence to: WELLS, ST. JOHN, ROBERTS,
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9 WA 99204-0317. Direct telephone calls to: David G. Latwesen, Ph.D.
10 (509) 624-4276.

11 I hereby declare that all statements made herein of my own
12 knowledge are true and that all statements made on information and
13 belief are believed to be true; and further that these statements were
14 made with the knowledge that willful false statements and the like so
15 made are punishable by fine or imprisonment, or both, under
16 Section 1001 of Title 18 of the United States Code and that such willful
17 false statement may jeopardize the validity of the application or any
18 patent issued therefrom.

* * * * * * * * * *

Full name of inventor: **Rickie C. Lake**

Inventor's Signature: 

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* * * * * * * * * * * -

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Priority Application Serial No. 09/392,073
Priority Filing Date September 8, 1999
Inventor Rickie C. Lake et al
Assignee Micron Technology, Inc.
Priority Group Art Unit 1751
Priority Examiner D. Hamlin
Attorney's Docket No. MI40-327
Title: An Epoxy, Epoxy System, and Method of Forming a Conductive
Adhesive Connection

To: Box Patent Application
Assistant Commissioner for Patents
Washington, D.C. 20231

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Date: 7/26/01



David G. Latwesen, Ph.D.
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